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## \*BIBDATASHEET\*

Bib Data Sheet

CONFIRMATION NO. 7266

SERIAL NUMBER 10/692,065	FILING DATE 10/23/2003 RULE	CLASS 257	GROUP ART UNIT 2818	ATTORNEY DOCKET NO. YOR920010216US2
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## \*\* CONTINUING DATA \*\*\*\*\*

This application is a CON of 10/052,620 01/18/2002 PAT 6,661,098

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 01/28/2004

Foreign Priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	NY	3	20	4
Verified and Acknowledged	Examiner's Signature Initials				

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## TITLE

High density area array solder microjoining interconnect structure and fabrication method

<input type="checkbox"/> All Fees
<input type="checkbox"/> 1.16 Fees ( Filing )